Renesas Electronics America Inc - M306N4MGT-153FPUTQ Datasheet

Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	M16C/60
Core Size	16-Bit
Speed	20MHz
Connectivity	CANbus, I²C, IEBus, SIO, UART/USART
Peripherals	DMA, WDT
Number of I/O	87
Program Memory Size	256KB (256K x 8)
Program Memory Type	Mask ROM
EEPROM Size	-
RAM Size	10K x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 26x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-BQFP
Supplier Device Package	100-QFP (14x20)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/m306n4mgt-153fputq

Notice

1. All information included in this document is current as of the date this document is issued. Such information, however, is subject to change without any prior notice. Before purchasing or using any Renesas Electronics products listed herein, please confirm the latest product information with a Renesas Electronics sales office. Also, please pay regular and careful attention to additional and different information to be disclosed by Renesas Electronics such as that disclosed through our website.
2. Renesas Electronics does not assume any liability for infringement of patents, copyrights, or other intellectual property rights of third parties by or arising from the use of Renesas Electronics products or technical information described in this document. No license, express, implied or otherwise, is granted hereby under any patents, copyrights or other intellectual property rights of Renesas Electronics or others.
3. You should not alter, modify, copy, or otherwise misappropriate any Renesas Electronics product, whether in whole or in part.
4. Descriptions of circuits, software and other related information in this document are provided only to illustrate the operation of semiconductor products and application examples. You are fully responsible for the incorporation of these circuits, software, and information in the design of your equipment. Renesas Electronics assumes no responsibility for any losses incurred by you or third parties arising from the use of these circuits, software, or information.
5. When exporting the products or technology described in this document, you should comply with the applicable export control laws and regulations and follow the procedures required by such laws and regulations. You should not use Renesas Electronics products or the technology described in this document for any purpose relating to military applications or use by the military, including but not limited to the development of weapons of mass destruction. Renesas Electronics products and technology may not be used for or incorporated into any products or systems whose manufacture, use, or sale is prohibited under any applicable domestic or foreign laws or regulations.
6. Renesas Electronics has used reasonable care in preparing the information included in this document, but Renesas Electronics does not warrant that such information is error free. Renesas Electronics assumes no liability whatsoever for any damages incurred by you resulting from errors in or omissions from the information included herein.
7. Renesas Electronics products are classified according to the following three quality grades: "Standard", "High Quality", and "Specific". The recommended applications for each Renesas Electronics product depends on the product's quality grade, as indicated below. You must check the quality grade of each Renesas Electronics product before using it in a particular application. You may not use any Renesas Electronics product for any application categorized as "Specific" without the prior written consent of Renesas Electronics. Further, you may not use any Renesas Electronics product for any application for which it is not intended without the prior written consent of Renesas Electronics. Renesas Electronics shall not be in any way liable for any damages or losses incurred by you or third parties arising from the use of any Renesas Electronics product for an application categorized as "Specific" or for which the product is not intended where you have failed to obtain the prior written consent of Renesas Electronics. The quality grade of each Renesas Electronics product is "Standard" unless otherwise expressly specified in a Renesas Electronics data sheets or data books, etc.

   "Standard": Computers; office equipment; communications equipment; test and measurement equipment; audio and visual equipment; home electronic appliances; machine tools; personal electronic equipment; and industrial robots.

   "High Quality": Transportation equipment (automobiles, trains, ships, etc.); traffic control systems; anti-disaster systems; anti-crime systems; safety equipment; and medical equipment not specifically designed for life support.

   "Specific": Aircraft; aerospace equipment; submersible repeaters; nuclear reactor control systems; medical equipment or systems for life support (e.g. artificial life support devices or systems), surgical implantations, or healthcare intervention (e.g. excision, etc.), and any other applications or purposes that pose a direct threat to human life.
8. You should use the Renesas Electronics products described in this document within the range specified by Renesas Electronics, especially with respect to the maximum rating, operating supply voltage range, movement power voltage range, heat radiation characteristics, installation and other product characteristics. Renesas Electronics shall have no liability for malfunctions or damages arising out of the use of Renesas Electronics products beyond such specified ranges.
9. Although Renesas Electronics endeavors to improve the quality and reliability of its products, semiconductor products have specific characteristics such as the occurrence of failure at a certain rate and malfunctions under certain use conditions. Further, Renesas Electronics products are not subject to radiation resistance design. Please be sure to implement safety measures to guard them against the possibility of physical injury, and injury or damage caused by fire in the event of the failure of a Renesas Electronics product, such as safety design for hardware and software including but not limited to redundancy, fire control and malfunction prevention, appropriate treatment for aging degradation or any other appropriate measures. Because the evaluation of microcomputer software alone is very difficult, please evaluate the safety of the final products or system manufactured by you.
10. Please contact a Renesas Electronics sales office for details as to environmental matters such as the environmental compatibility of each Renesas Electronics product. Please use Renesas Electronics products in compliance with all applicable laws and regulations that regulate the inclusion or use of controlled substances, including without limitation, the EU RoHS Directive. Renesas Electronics assumes no liability for damages or losses occurring as a result of your noncompliance with applicable laws and regulations.
11. This document may not be reproduced or duplicated, in any form, in whole or in part, without prior written consent of Renesas Electronics.
12. Please contact a Renesas Electronics sales office if you have any questions regarding the information contained in this document or Renesas Electronics products, or if you have any other inquiries.

(Note 1) "Renesas Electronics" as used in this document means Renesas Electronics Corporation and also includes its majority-owned subsidiaries.

(Note 2) "Renesas Electronics product(s)" means any product developed or manufactured by or for Renesas Electronics.

1.2 Performance Overview

Table 1.1 lists the Functions and Specifications for M16C/6N Group (M16C/6N4).

Table 1.1 Functions and Specifications for M16C/6N Group (M16C/6N4)

Item			Specification	
			Normal-ver.	T/V-ver.
CPU	Number of fundamental instructions		91 instructions	
	Minimum instruction execution time		41.7 ns (f(BCLK) = 24 MHz, 1/1 prescaler, without software wait)	50.0 ns (f(BCLK) = 20 MHz, 1/1 prescaler, without software wait)
	Operating mode		Single-chip, memory expansion, and microprocessor modes	
	Address space		1 Mbyte	
	Memory capacity		Refer to **Table 1.2 Product Information**	
Peripheral Function	Ports		Input/Output: 87 pins, Input: 1 pin	
	Multifunction timers		Timer A: 16 bits × 5 channels Timer B: 16 bits × 6 channels Three-phase motor control circuit	
	Serial interfaces		3 channels Clock synchronous, UART, I²C-bus (1), IEBus (2) 1 channel Clock synchronous	
	A/D converter		10-bit A/D converter: 1 circuit, 26 channels	
	D/A converter		8 bits × 2 channels	
	DMAC		2 channels	
	CRC calculation circuit		CRC-CCITT	
	CAN module		2 channels with 2.0B specification	
	Watchdog timer		15 bits × 1 channel (with prescaler)	
	Interrupts		Internal: 31 sources, External: 9 sources Software: 4 sources, Priority levels: 7 levels	
	Clock generation circuits		4 circuits • Main clock oscillation circuit (*) • Sub clock oscillation circuit (*) • On-chip oscillator • PLL frequency synthesizer (*) Equipped with on-chip feedback resistor	
	Oscillation-stopped detector		Main clock oscillation stop and re-oscillation detection function	
Electrical Characteristics	Supply voltage		VCC = 3.0 to 5.5 V (f(BCLK) = 24 MHz, 1/1 prescaler, without software wait)	VCC = 4.2 to 5.5 V (f(BCLK) = 20 MHz, 1/1 prescaler, without software wait)
	Consumption current	Mask ROM	20 mA (f(BCLK) = 24 MHz, PLL operation, no division)	18 mA (f(BCLK) = 20 MHz, PLL operation, no division)
		Flash memory	22 mA (f(BCLK) = 24 MHz, PLL operation, no division)	20 mA (f(BCLK) = 20 MHz, PLL operation, no division)
		Mask ROM	3 µA (f(BCLK) = 32 kHz, Wait mode, Oscillation capacity Low)	
		Flash memory	0.8 µA (Stop mode, Topr = 25°C)	
Flash Memory Version	Programming and erasure voltage		3.0 ± 0.3 V or 5.0 ± 0.5 V	5.0 ± 0.5 V
	Programming and erasure endurance		100 times	
I/O Characteristics	I/O withstand voltage		5.0 V	
	Output current		5 mA	
Operating Ambient Temperature			-40 to 85°C	T version: -40 to 85°C V version: -40 to 125°C (option)
Device Configuration			CMOS high-performance silicon gate	
Package			100-pin molded-plastic QFP, LQFP	

NOTES:
1. I²C-bus is a trademark of Koninklijke Philips Electronics N.V.
2. IEBus is a trademark of NEC Electronics Corporation.

option: All options are on request basis.

Table 1.6 Pin Functions (2)

Signal Name	Pin Name	I/O Type	Description
Main clock input	XIN	I	I/O pins for the main clock oscillation circuit. Connect a ceramic resonator or crystal oscillator between XIN and XOUT (1).
Main clock output	XOUT	O	To use the external clock, input the clock from XIN and leave XOUT open.
Sub clock input	XCIN	I	I/O pins for a sub clock oscillation circuit. Connect a crystal oscillator between XCIN and XCOUT (1).
Sub clock output	XCOUT	O	To use the external clock, input the clock from XCIN and leave XCOUT open.
BCLK output	BCLK	O	Outputs the BCLK signal.
Clock output	CLKOUT	O	The clock of the same cycle as fC, f8, or f32 is output.
INT interrupt input	INT0 to INT5	I	Input pins for the INT interrupt.
NMI interrupt input	NMI	I	Input pin for the NMI interrupt.
Key input interrupt input	KI0 to KI3	I	Input pins for the key input interrupt.
Timer A	TA0OUT to TA4OUT	I/O	These are timer A0 to timer A4 I/O pins.
	TA0IN to TA4IN	I	These are timer A0 to timer A4 input pins.
	ZP	I	Input pin for the Z-phase.
Timer B	TB0IN to TB5IN	I	These are timer B0 to timer B5 input pins.
Three-phase motor control output	U, U, V, V, W, W	O	These are Three-phase motor control output pins.
Serial interface	CTS0 to CTS2	I	These are transmit control input pins.
	RTS0 to RTS2	O	These are receive control output pins.
	CLK0 to CLK3	I/O	These are transfer clock I/O pins.
	RXD0 to RXD2	I	These are serial data input pins.
	SIN3	I	These are serial data input pins.
	TXD0 to TXD2	O	These are serial data output pins.
	SOUT3	O	These are serial data output pins.
	CLKS1	O	This is output pin for transfer clock output from multiple pins function.
I^2C mode	SDA0 to SDA2	I/O	These are serial data I/O pins.
	SCL0 to SCL2	I/O	These are transfer clock I/O pins. (however, SCL2 for the N-channel open drain output.)
Reference voltage input	VREF	I	Applies the reference voltage for the A/D converter and D/A converter.
A/D converter	AN0 to AN7 AN0_0 to AN0_7 AN2_0 to AN2_7	I	Analog input pins for the A/D converter.
	ADTRG	I	This is an A/D trigger input pin.
	ANEX0	I/O	This is the extended analog input pin for the A/D converter, and is the output in external op-amp connection mode.
	ANEX1	I	This is the extended analog input pin for the A/D converter.
D/A converter	DA0, DA1	O	These are the output pins for the D/A converter.
CAN module	CRX0, CRX1	I	These are the input pins for the CAN module.
	CTX0, CTX1	O	These are the output pins for the CAN module.

I: Input O: Output I/O: Input/Output

NOTE:
1. Ask the oscillator maker the oscillation characteristic.

2. Central Processing Unit (CPU)

Figure 2.1 shows the CPU Registers. The CPU has 13 registers. Of these, R0, R1, R2, R3, A0, A1, and FB configure a register bank. There are two register banks.

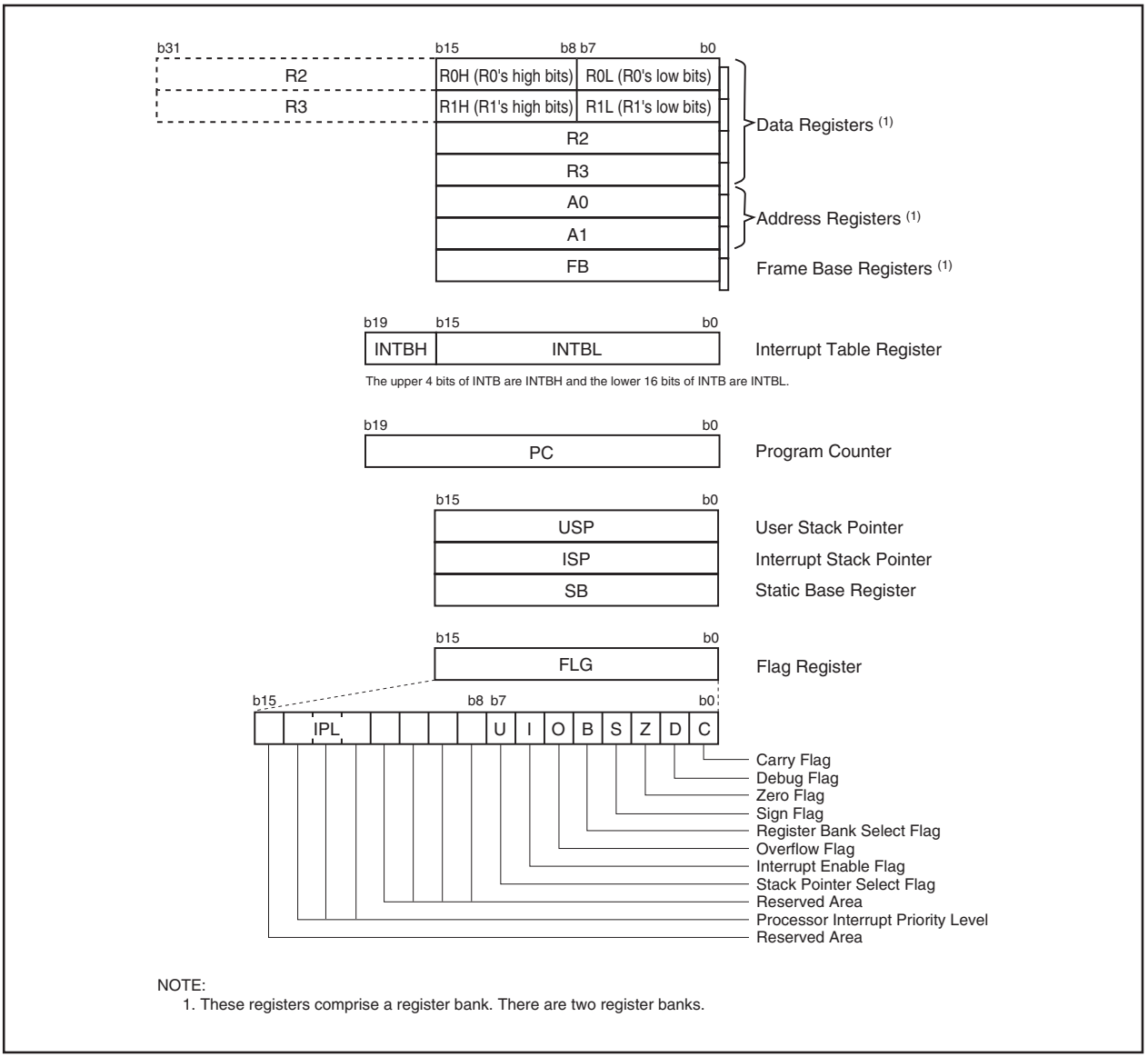


Figure 2.1 CPU Registers

2.1 Data Registers (R0, R1, R2, and R3)

The R0 register consists of 16 bits, and is used mainly for transfers and arithmetic/logic operations. R1 to R3 are the same as R0.

The R0 register can be separated between high (R0H) and low (R0L) for use as two 8-bit data registers. R1H and R1L are the same as R0H and R0L. Conversely R2 and R0 can be combined for use as a 32-bit data register (R2R0). R3R1 is analogous to R2R0.

2.2 Address Registers (A0 and A1)

The A0 register consists of 16 bits, and is used for address register indirect addressing and address register relative addressing. They also are used for transfers and arithmetic/logic operations. A1 is the same as A0.

In some instructions, A1 and A0 can be combined for use as a 32-bit address register (A1A0).

Table 4.12 SFR Information (12)

Address	Register	Symbol	After Reset
02C0h	CAN1 Message Box 6: Identifier / DLC		XXh
02C1h			XXh
02C2h			XXh
02C3h			XXh
02C4h			XXh
02C5h			XXh
02C6h	CAN1 Message Box 6: Data Field		XXh
02C7h			XXh
02C8h			XXh
02C9h			XXh
02CAh			XXh
02CBh			XXh
02CCh			XXh
02CDh			XXh
02CEh	CAN1 Message Box 6: Time Stamp		XXh
02CFh			XXh
02D0h	CAN1 Message Box 7: Identifier / DLC		XXh
02D1h			XXh
02D2h			XXh
02D3h			XXh
02D4h			XXh
02D5h			XXh
02D6h	CAN1 Message Box 7: Data Field		XXh
02D7h			XXh
02D8h			XXh
02D9h			XXh
02DAh			XXh
02DBh			XXh
02DCh			XXh
02DDh			XXh
02DEh	CAN1 Message Box 7: Time Stamp		XXh
02DFh			XXh
02E0h	CAN1 Message Box 8: Identifier / DLC		XXh
02E1h			XXh
02E2h			XXh
02E3h			XXh
02E4h			XXh
02E5h			XXh
02E6h	CAN1 Message Box 8: Data Field		XXh
02E7h			XXh
02E8h			XXh
02E9h			XXh
02EAh			XXh
02EBh			XXh
02ECh			XXh
02EDh			XXh
02EEh	CAN1 Message Box 8: Time Stamp		XXh
02EFh			XXh
02F0h	CAN1 Message Box 9: Identifier / DLC		XXh
02F1h			XXh
02F2h			XXh
02F3h			XXh
02F4h			XXh
02F5h			XXh
02F6h	CAN1 Message Box 9: Data Field		XXh
02F7h			XXh
02F8h			XXh
02F9h			XXh
02FAh			XXh
02FBh			XXh
02FCh			XXh
02FDh			XXh
02FEh	CAN1 Message Box 9: Time Stamp		XXh
02FFh			XXh

X: Undefined

Table 4.16 SFR Information (16) (2)

Address	Register	Symbol	After Reset
03C0h	A/D Register 0	AD0	XXh
03C1h			XXh
03C2h	A/D Register 1	AD1	XXh
03C3h			XXh
03C4h	A/D Register 2	AD2	XXh
03C5h			XXh
03C6h	A/D Register 3	AD3	XXh
03C7h			XXh
03C8h	A/D Register 4	AD4	XXh
03C9h			XXh
03CAh	A/D Register 5	AD5	XXh
03CBh			XXh
03CCh	A/D Register 6	AD6	XXh
03CDh			XXh
03CEh	A/D Register 7	AD7	XXh
03CFh			XXh
03D0h			
03D1h			
03D2h			
03D3h			
03D4h	A/D Control Register 2	ADCON2	00h
03D5h			
03D6h	A/D Control Register 0	ADCON0	00000XXXb
03D7h	A/D Control Register 1	ADCON1	00h
03D8h	D/A Register 0	DA0	00h
03D9h			
03DAh	D/A Register 1	DA1	00h
03DBh			
03DCh	D/A Control Register	DACON	00h
03DDh			
03DEh			
03DFh			
03E0h	Port P0 Register	P0	XXh
03E1h	Port P1 Register	P1	XXh
03E2h	Port P0 Direction Register	PD0	00h
03E3h	Port P1 Direction Register	PD1	00h
03E4h	Port P2 Register	P2	XXh
03E5h	Port P3 Register	P3	XXh
03E6h	Port P2 Direction Register	PD2	00h
03E7h	Port P3 Direction Register	PD3	00h
03E8h	Port P4 Register	P4	XXh
03E9h	Port P5 Register	P5	XXh
03EAh	Port P4 Direction Register	PD4	00h
03EBh	Port P5 Direction Register	PD5	00h
03ECh	Port P6 Register	P6	XXh
03EDh	Port P7 Register	P7	XXh
03EEh	Port P6 Direction Register	PD6	00h
03EFh	Port P7 Direction Register	PD7	00h
03F0h	Port P8 Register	P8	XXh
03F1h	Port P9 Register	P9	XXh
03F2h	Port P8 Direction Register	PD8	00X00000b
03F3h	Port P9 Direction Register	PD9	00h
03F4h	Port P10 Register	P10	XXh
03F5h			
03F6h	Port P10 Direction Register	PD10	00h
03F7h			
03F8h			
03F9h			
03FAh			
03FBh			
03FCh	Pull-up Control Register 0	PUR0	00h
03FDh	Pull-up Control Register 1	PUR1	00000000b (1) 00000010b
03FEh	Pull-up Control Register 2	PUR2	00h
03FFh	Port Control Register	PCR	00h

X: Undefined

NOTES:
1. At hardware reset, the register is as follows:
   - 00000000b where "L" is input to the CNVSS pin
   - 00000010b where "H" is input to the CNVSS pin

   At software reset, watchdog timer reset and oscillation stop detection reset, the register is as follows:
   - 00000000b where bits PM01 to PM00 in the PM0 register are 00b (single-chip mode)
   - 00000010b where bits PM01 to PM00 in the PM0 register are 01b (memory expansion mode) or 11b (microprocessor mode)
2. Blank spaces are reserved. No access is allowed.

Table 5.5 Electrical Characteristics (2) [1]

Symbol	Parameter		Measuring Condition		Standard			Unit
					Min.	Typ.	Max.	
I_{CC}	Power supply current (VCC = 4.2 to 5.5 V)	In single-chip mode, the output pins are open and other pins are VSS.	Mask ROM	f(BCLK) = 20 MHz, PLL operation, No division		18	32	mA
				On-chip oscillation, No division		1		mA
			Flash memory	f(BCLK) = 20 MHz, PLL operation, No division		20	34	mA
				On-chip oscillation, No division		1.8		mA
			Flash memory program	f(BCLK) = 10 MHz, VCC = 5 V		15		mA
			Flash memory erase	f(BCLK) = 10 MHz, VCC = 5 V		25		mA
			Mask ROM	f(BCLK) = 32kHz, Low power dissipation mode, ROM [2]		25		µA
			Flash memory	f(BCLK) = 32 kHz, Low power dissipation mode, RAM [2]		25		µA
				f(BCLK) = 32 kHz, Low power dissipation mode, Flash memory [2]		420		µA
			Mask ROM Flash memory	On-chip oscillation, Wait mode		50		µA
				f(BCLK) = 32 kHz, Wait mode [3], Oscillation capacity High		8.5		µA
				f(BCLK) = 32 kHz, Wait mode [3], Oscillation capacity Low		3.0		µA
				Stop mode, Topr = 25°C		0.8	3.0	µA

NOTES:
1. Referenced to VCC = 4.2 to 5.5 V, VSS = 0 V at Topr = –40 to 85°C, f(BCLK) = 20 MHz unless otherwise specified.
2. This indicates the memory in which the program to be executed exists.
3. With one timer operated using fC32.

Table 5.6 A/D Conversion Characteristics (1)

Symbol	Parameter		Measuring Condition		Standard			Unit
					Min.	Typ.	Max.	
–	Resolution		VREF = VCC				10	Bit
INL	Integral nonlinearity error	10 bits	VREF = VCC = 5 V	ANEX0, ANEX1 input, AN0 to AN7 input, AN0_0 to AN0_7 input, AN2_0 to AN2_7 input			±3	LSB
				External operation amp connection mode			±7	LSB
		8 bits	VREF = AVCC = VCC = 5 V				±2	LSB
–	Absolute accuracy	10 bits	VREF = VCC = 5 V	ANEX0, ANEX1 input, AN0 to AN7 input, AN0_0 to AN0_7 input, AN2_0 to AN2_7 input			±3	LSB
				External operation amp connection mode			±7	LSB
		8 bits	VREF = AVCC = VCC = 5 V				±2	LSB
DNL	Differential nonlinearity error						±1	LSB
–	Offset error						±3	LSB
–	Gain error						±3	LSB
R_{LADDER}	Resistor ladder		VREF = VCC		10		40	kΩ
t_{CONV}	10-bit conversion time, sample & hold available		VREF = VCC = 5 V, ϕAD = 10 MHz		3.3			µs
	8-bit conversion time, sample & hold available		VREF = VCC = 5 V, ϕAD = 10 MHz		2.8			µs
t_{SAMP}	Sampling time				0.3			µs
V_{REF}	Reference voltage				2.0		V_{CC}	V
V_{IA}	Analog input voltage				0		V_{REF}	V

NOTES:
1. Referenced to VCC = AVCC = VREF = 4.2 to 5.5 V, VSS = AVSS = 0 V, –40 to 85°C unless otherwise specified.
2. ϕAD frequency must be 10 MHz or less.
3. When sample & hold is disabled, ϕAD frequency must be 250kHz or more in addition to a limit of NOTE 2.
   When sample & hold is enabled, ϕAD frequency must be 1MHz or more in addition to a limit of NOTE 2.

Table 5.7 D/A conversion Characteristics (1)

Symbol	Parameter	Measuring condition	Standard			Unit
			Min.	Typ.	Max.	
–	Resolution				8	Bits
–	Absolute accuracy				1.0	%
t_{su}	Setup time				3	µs
R_O	Output resistance		4	10	20	kΩ
I_{VREF}	Reference power supply input current	(NOTE 2)			1.5	mA

NOTES:
1. Referenced to VCC = AVCC = VREF = 4.2 to 5.5 V, VSS = AVSS = 0 V, –40 to 85°C unless otherwise specified.
2. This applies when using one D/A converter, with the DAi register (i = 0, 1) for the unused D/A converter set to 00h. The resistor ladder of the A/D converter is not included. Also, the I_{VREF} will flow even if VREF is disconnected by the ADCON1 register.

Timing Requirements

VCC = 5 V

(Referenced to VCC = 5 V, VSS = 0 V, at Topr = –40 to 85°C unless otherwise specified)

Table 5.9 External Clock Input (XIN Input)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
t_c	External clock input cycle time	62.5		ns
$t_{w(H)}$	External clock input HIGH pulse width	25		ns
$t_{w(L)}$	External clock input LOW pulse width	25		ns
t_r	External clock rise time		15	ns
t_f	External clock fall time		15	ns

Table 5.10 Memory Expansion Mode and Microprocessor Mode

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{ac1(RD-DB)}$	Data input access time (for setting with no wait)		(NOTE 1)	ns
$t_{ac2(RD-DB)}$	Data input access time (for setting with wait)		(NOTE 2)	ns
$t_{ac3(RD-DB)}$	Data input access time (when accessing multiplexed bus area)		(NOTE 3)	ns
$t_{su(DB-RD)}$	Data input setup time	40		ns
$t_{su(RDY-BCLK)}$	$\overline{RDY}$ input setup time	30		ns
$t_{su(HOLD-BCLK)}$	$\overline{HOLD}$ input setup time	40		ns
$t_{h(RD-DB)}$	Data input hold time	0		ns
$t_{h(BCLK-RDY)}$	$\overline{RDY}$ input hold time	0		ns
$t_{h(BCLK-HOLD)}$	$\overline{HOLD}$ input hold time	0		ns

NOTES:

1. Calculated according to the BCLK frequency as follows:

$$\frac{0.5 \times 10^9}{f(BCLK)} - 45 \text{ [ns]}$$

2. Calculated according to the BCLK frequency as follows:

$$\frac{(n - 0.5) \times 10^9}{f(BCLK)} - 45 \text{ [ns]}$$

n is “2” for 1-wait setting, “3” for 2-wait setting and “4” for 3-wait setting.

3. Calculated according to the BCLK frequency as follows:

$$\frac{(n - 0.5) \times 10^9}{f(BCLK)} - 45 \text{ [ns]}$$

n is “2” for 2-wait setting, “3” for 3-wait setting.

Timing Requirements

VCC = 5 V

(Referenced to VCC = 5 V, VSS = 0 V, at Topr = –40 to 85°C unless otherwise specified)

Table 5.17 Timer B Input (Counter Input in Event Counter Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TB)}$	TBiIN input cycle time (counted on one edge)	100		ns
$t_{w(TBH)}$	TBiIN input HIGH pulse width (counted on one edge)	40		ns
$t_{w(TBL)}$	TBiIN input LOW pulse width (counted on one edge)	40		ns
$t_{c(TB)}$	TBiIN input cycle time (counted on both edges)	200		ns
$t_{w(TBH)}$	TBiIN input HIGH pulse width (counted on both edges)	80		ns
$t_{w(TBL)}$	TBiIN input LOW pulse width (counted on both edges)	80		ns

Table 5.18 Timer B Input (Pulse Period Measurement Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TB)}$	TBiIN input cycle time	400		ns
$t_{w(TBH)}$	TBiIN input HIGH pulse width	200		ns
$t_{w(TBL)}$	TBiIN input LOW pulse width	200		ns

Table 5.19 Timer B Input (Pulse Width Measurement Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TB)}$	TBiIN input cycle time	400		ns
$t_{w(TBH)}$	TBiIN input HIGH pulse width	200		ns
$t_{w(TBL)}$	TBiIN input LOW pulse width	200		ns

Table 5.20 A/D Trigger Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{C(AD)}$	$\overline{\text{ADTRG}}$ input cycle time (trigger able minimum)	1000		ns
$t_{w(ADL)}$	$\overline{\text{ADTRG}}$ input LOW pulse width	125		ns

Table 5.21 Serial Interface

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLKi input cycle time	200		ns
$t_{w(CKH)}$	CLKi input HIGH pulse width	100		ns
$t_{w(CKL)}$	CLKi input LOW pulse width	100		ns
$t_{d(C-Q)}$	TXDi output delay time		80	ns
$t_{h(C-Q)}$	TXDi hold time	0		ns
$t_{su(D-C)}$	RXDi input setup time	70		ns
$t_{h(C-D)}$	RXDi input hold time	90		ns

Table 5.22 External Interrupt $\overline{\text{INTi}}$ Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(INH)}$	$\overline{\text{INTi}}$ input HIGH pulse width	250		ns
$t_{w(INL)}$	$\overline{\text{INTi}}$ input LOW pulse width	250		ns

Switching Characteristics VCC = 5 V

(Referenced to VCC = 5 V, VSS = 0 V, at Topr = –40 to 85 °C unless otherwise specified)

Table 5.23 Memory Expansion Mode and Microprocessor Mode (for setting with no wait)

Symbol	Parameter	Measuring Condition	Standard		Unit
			Min.	Max.	
$t_{d(BCLK-AD)}$	Address output delay time	Figure 5.2		25	ns
$t_{h(BCLK-AD)}$	Address output hold time (in relation to BCLK)		4		ns
$t_{h(RD-AD)}$	Address output hold time (in relation to RD)		0		ns
$t_{h(WR-AD)}$	Address output hold time (in relation to WR)		(NOTE 1)		ns
$t_{d(BCLK-CS)}$	Chip select output delay time			25	ns
$t_{h(BCLK-CS)}$	Chip select output hold time (in relation to BCLK)		4		ns
$t_{d(BCLK-ALE)}$	ALE signal output delay time			15	ns
$t_{h(BCLK-ALE)}$	ALE signal output hold time		–4		ns
$t_{d(BCLK-RD)}$	RD signal output delay time			25	ns
$t_{h(BCLK-RD)}$	RD signal output hold time		0		ns
$t_{d(BCLK-WR)}$	WR signal output delay time			25	ns
$t_{h(BCLK-WR)}$	WR signal output hold time		0		ns
$t_{d(BCLK-DB)}$	Data output delay time (in relation to BCLK)			40	ns
$t_{h(BCLK-DB)}$	Data output hold time (in relation to BCLK) (3)		4		ns
$t_{d(DB-WR)}$	Data output delay time (in relation to WR)		(NOTE 2)		ns
$t_{h(WR-DB)}$	Data output hold time (in relation to WR) (3)		(NOTE 1)		ns
$t_{d(BCLK-HLDA)}$	$\overline{HLDA}$ output delay time			40	ns

NOTES:

1. Calculated according to the BCLK frequency as follows:

$$\frac{0.5 \times 10^9}{f(BCLK)} - 10 \text{ [ns]}$$

2. Calculated according to the BCLK frequency as follows:

$$\frac{0.5 \times 10^9}{f(BCLK)} - 40 \text{ [ns]}$$ f(BCLK) is 12.5 MHz or less.

3. This standard value shows the timing when the output is off, and does not show hold time of data bus.
   Hold time of data bus varies with capacitor volume and pull-up (pull-down) resistance value.
   Hold time of data bus is expressed in
   $t = -CR \times \ln (1 - V_{OL} / V_{CC})$
   by a circuit of the right figure.
   For example, when $V_{OL} = 0.2\ V_{CC}$, C = 30 pF, R =1 kΩ, hold time of output "L" level is
   $t = -30\text{ pF} \times 1\text{ k}\Omega \times \ln (1 - 0.2\ V_{CC} / V_{CC}) = 6.7$ ns.

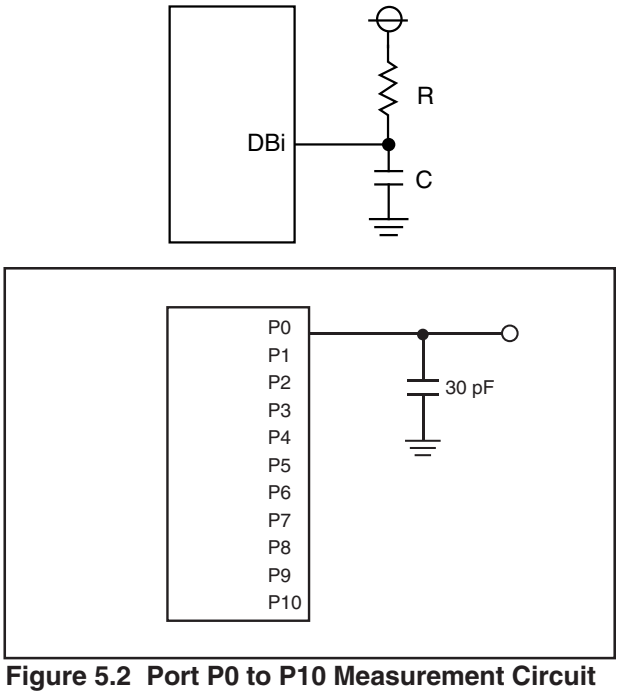


Figure 5.2 Port P0 to P10 Measurement Circuit

5.2 Electrical Characteristics (Normal-ver.)

Table 5.26 Absolute Maximum Ratings

Symbol	Parameter		Condition	Rated Value	Unit
V_{CC}	Supply voltage (VCC1 = VCC2)		VCC = AVCC	–0.3 to 6.5	V
AV_{CC}	Analog supply voltage		VCC = AVCC	–0.3 to 6.5	V
V_I	Input voltage	$\overline{RESET}$, CNVSS, BYTE, P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0, P7_2 to P7_7, P8_0 to P8_7, P9_0, P9_2 to P9_7, P10_0 to P10_7, VREF, XIN		–0.3 to VCC+0.3	V
		P7_1, P9_1		–0.3 to 6.5	V
V_O	Output voltage	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0, P7_2 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0, P9_2 to P9_7, P10_0 to P10_7, XOUT		–0.3 to VCC+0.3	V
		P7_1, P9_1		–0.3 to 6.5	V
P_d	Power dissipation		Topr = 25°C	700	mW
T_{opr}	Operating ambient temperature	During MCU operation		–40 to 85	°C
		During flash memory program and erase operation		0 to 60	
T_{stg}	Storage temperature			–65 to 150	°C

Table 5.27 Recommended Operating Conditions (1) [1]

Symbol	Parameter		Standard			Unit
			Min.	Typ.	Max.	
V_{CC}	Supply voltage (VCC1 = VCC2)		3.0	5.0	5.5	V
AV_{CC}	Analog supply voltage			V_{CC}		V
V_{SS}	Supply voltage			0		V
AV_{SS}	Analog supply voltage			0		V
V_{IH}	HIGH input voltage	P3_1 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0, P7_2 to P7_7, P8_0 to P8_7, P9_0, P9_2 to P9_7, P10_0 to P10_7, XIN, $\overline{\text{RESET}}$, CNVSS, BYTE	0.8 V_{CC}		V_{CC}	V
		P7_1, P9_1	0.8 V_{CC}		6.5	V
		P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 (During single-chip mode)	0.8 V_{CC}		V_{CC}	V
		P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 (Data input during memory expansion and microprocessor modes)	0.5 V_{CC}		V_{CC}	V
V_{IL}	LOW input voltage	P3_1 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_7, P9_0 to P9_7, P10_0 to P10_7, XIN, $\overline{\text{RESET}}$, CNVSS, BYTE	0		0.2 V_{CC}	V
		P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 (During single-chip mode)	0		0.2 V_{CC}	V
		P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 (Data input during memory expansion and microprocessor modes)	0		0.16 V_{CC}	V
$I_{OH(peak)}$	HIGH peak output current	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0, P7_2 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0, P9_2 to P9_7, P10_0 to P10_7			–10.0	mA
$I_{OH(avg)}$	HIGH average output current	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0, P7_2 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0, P9_2 to P9_7, P10_0 to P10_7			–5.0	mA
$I_{OL(peak)}$	LOW peak output current	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7			10.0	mA
$I_{OL(avg)}$	LOW average output current	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7			5.0	mA

NOTES:

1. Referenced to VCC = 3.0 to 5.5 V at Topr = –40 to 85°C unless otherwise specified.
2. Average output current values during 100 ms period.
3. The total $I_{OL(peak)}$ for ports P0, P1, P2, P8_6, P8_7, P9, and P10 must be 80 mA max.
   The total $I_{OL(peak)}$ for ports P3, P4, P5, P6, P7, and P8_0 to P8_4 must be 80 mA max.
   The total $I_{OH(peak)}$ for ports P0, P1, and P2 must be –40 mA max.
   The total $I_{OH(peak)}$ for ports P3, P4, and P5 must be –40 mA max.
   The total $I_{OH(peak)}$ for ports P6, P7, and P8_0 to P8_4 must be –40 mA max.
   The total $I_{OH(peak)}$ for ports P8_6, P8_7, P9, and P10 must be –40 mA max.

Timing Requirements

VCC = 5 V

(Referenced to VCC = 5 V, VSS = 0 V, at Topr = –40 to 85°C unless otherwise specified)

Table 5.34 External Clock Input (XIN Input)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
t_c	External clock input cycle time	62.5		ns
$t_{w(H)}$	External clock input HIGH pulse width	25		ns
$t_{w(L)}$	External clock input LOW pulse width	25		ns
t_r	External clock rise time		15	ns
t_f	External clock fall time		15	ns

Table 5.35 Memory Expansion Mode and Microprocessor Mode

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{ac1(RD-DB)}$	Data input access time (for setting with no wait)		(NOTE 1)	ns
$t_{ac2(RD-DB)}$	Data input access time (for setting with wait)		(NOTE 2)	ns
$t_{ac3(RD-DB)}$	Data input access time (when accessing multiplexed bus area)		(NOTE 3)	ns
$t_{su(DB-RD)}$	Data input setup time	40		ns
$t_{su(RDY-BCLK)}$	$\overline{RDY}$ input setup time	30		ns
$t_{su(HOLD-BCLK)}$	$\overline{HOLD}$ input setup time	40		ns
$t_{h(RD-DB)}$	Data input hold time	0		ns
$t_{h(BCLK-RDY)}$	$\overline{RDY}$ input hold time	0		ns
$t_{h(BCLK-HOLD)}$	$\overline{HOLD}$ input hold time	0		ns

NOTES:

1. Calculated according to the BCLK frequency as follows:

$$\frac{0.5 \times 10^9}{f(BCLK)} - 45 \text{ [ns]}$$

2. Calculated according to the BCLK frequency as follows:

$$\frac{(n - 0.5) \times 10^9}{f(BCLK)} - 45 \text{ [ns]}$$

n is “2” for 1-wait setting, “3” for 2-wait setting and “4” for 3-wait setting.

3. Calculated according to the BCLK frequency as follows:

$$\frac{(n - 0.5) \times 10^9}{f(BCLK)} - 45 \text{ [ns]}$$

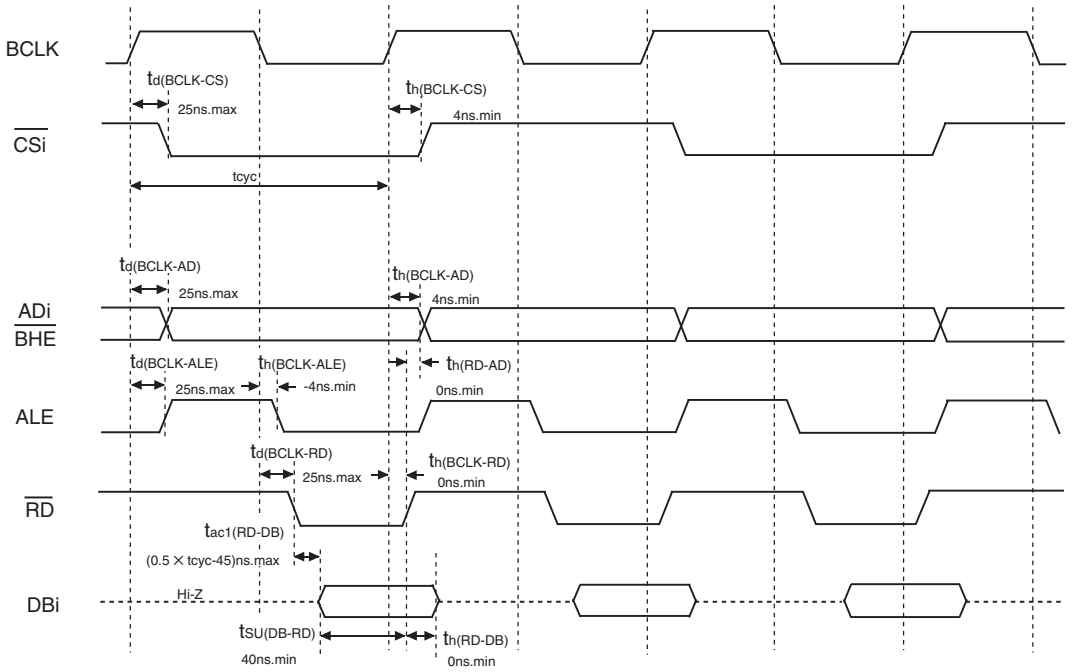
n is “2” for 2-wait setting, “3” for 3-wait setting.

Memory Expansion Mode and Microprocessor Mode

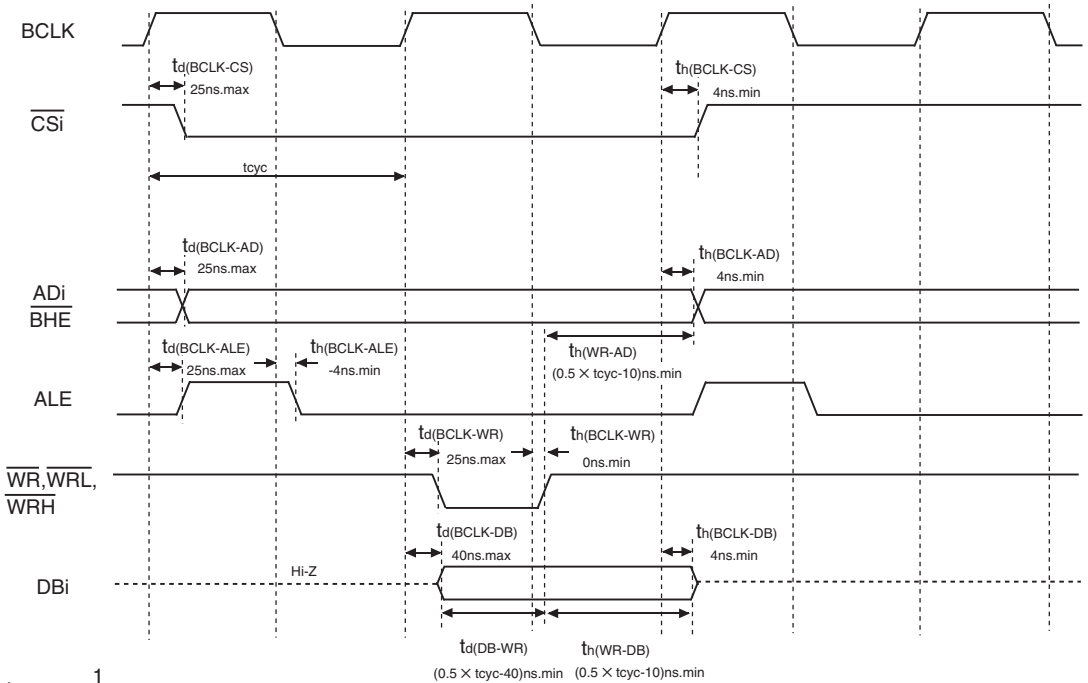
VCC = 5 V

(For setting with no wait)

Read timing



Write timing



$$tcyc = \frac{1}{f(BCLK)}$$

Measuring conditions :

- VCC = 5 V
- Input timing voltage : V_{IL} = 0.8 V, V_{IH} = 2.0 V
- Output timing voltage : V_{OL} = 0.4 V, V_{OH} = 2.4 V

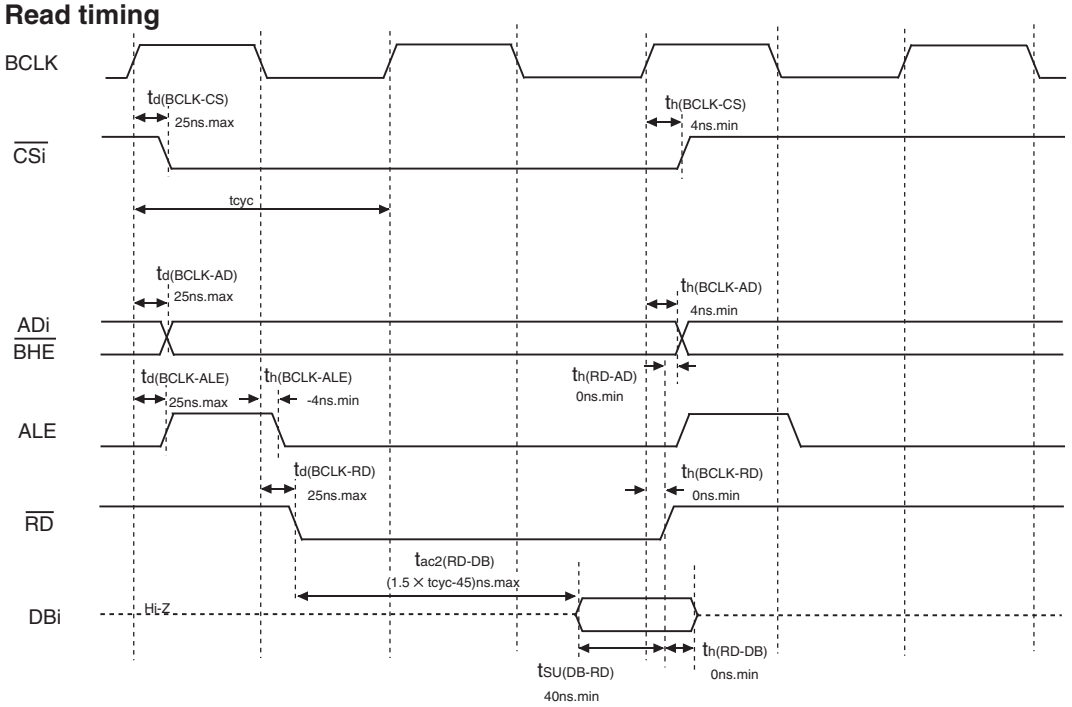
Figure 5.15 Timing Diagram (3)

Memory Expansion Mode and Microprocessor Mode

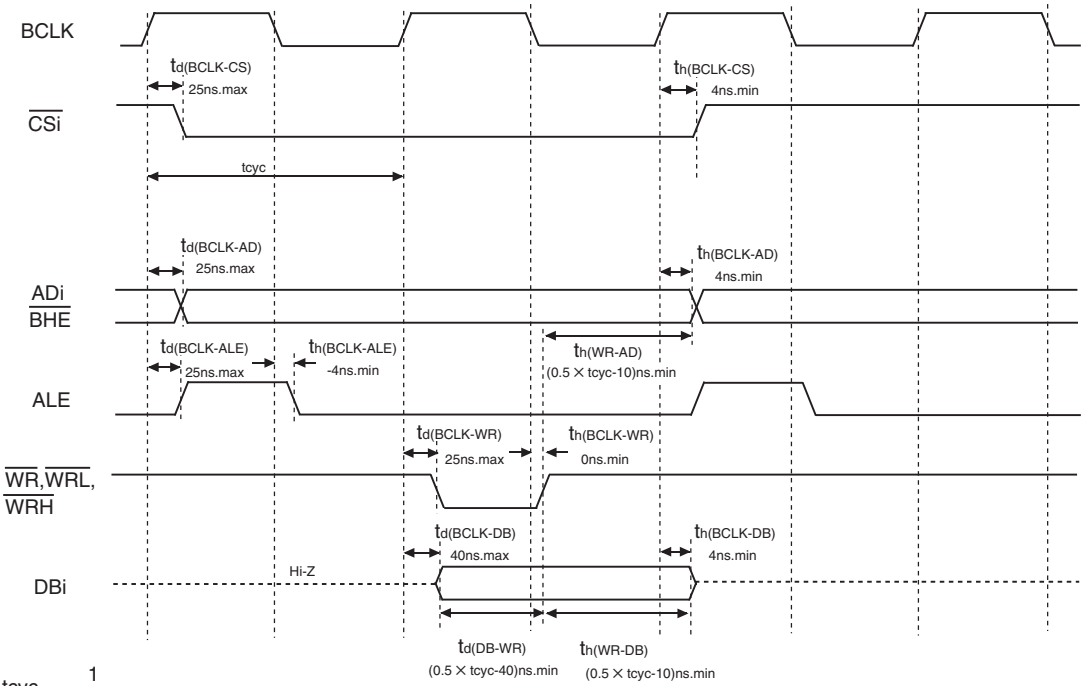
VCC = 5 V

(For 1-wait setting and external area access)

Read timing



Write timing



$$tcyc = \frac{1}{f(BCLK)}$$

Measuring conditions :

- VCC = 5 V
- Input timing voltage : V_{IL} = 0.8 V, V_{IH} = 2.0 V
- Output timing voltage : V_{OL} = 0.4 V, V_{OH} = 2.4 V

Figure 5.16 Timing Diagram (4)

Switching Characteristics

VCC = 3.3 V

(Referenced to VCC = 3.3 V, VSS = 0 V, at Topr = –40 to 85 °C unless otherwise specified)

Table 5.66 Memory Expansion Mode and Microprocessor Mode (for setting with no wait)

Symbol	Parameter	Measuring Condition	Standard		Unit
			Min.	Max.	
$t_{d(BCLK-AD)}$	Address output delay time	Figure 5.21		30	ns
$t_{h(BCLK-AD)}$	Address output hold time (in relation to BCLK)		4		ns
$t_{h(RD-AD)}$	Address output hold time (in relation to RD)		0		ns
$t_{h(WR-AD)}$	Address output hold time (in relation to WR)		(NOTE 1)		ns
$t_{d(BCLK-CS)}$	Chip select output delay time			30	ns
$t_{h(BCLK-CS)}$	Chip select output hold time (in relation to BCLK)		4		ns
$t_{d(BCLK-ALE)}$	ALE signal output delay time			25	ns
$t_{h(BCLK-ALE)}$	ALE signal output hold time		–4		ns
$t_{d(BCLK-RD)}$	RD signal output delay time			30	ns
$t_{h(BCLK-RD)}$	RD signal output hold time		0		ns
$t_{d(BCLK-WR)}$	WR signal output delay time			30	ns
$t_{h(BCLK-WR)}$	WR signal output hold time		0		ns
$t_{d(BCLK-DB)}$	Data output delay time (in relation to BCLK)			40	ns
$t_{h(BCLK-DB)}$	Data output hold time (in relation to BCLK) (3)		4		ns
$t_{d(DB-WR)}$	Data output delay time (in relation to WR)		(NOTE 2)		ns
$t_{h(WR-DB)}$	Data output hold time (in relation to WR) (3)		(NOTE 1)		ns
$t_{d(BCLK-HLDA)}$	$\overline{HLDA}$ output delay time			40	ns

NOTES:

1. Calculated according to the BCLK frequency as follows:

$$\frac{0.5 \times 10^9}{f(BCLK)} - 10 \text{ [ns]}$$

2. Calculated according to the BCLK frequency as follows:

$$\frac{0.5 \times 10^9}{f(BCLK)} - 40 \text{ [ns]}$$ f(BCLK) is 12.5 MHz or less.

3. This standard value shows the timing when the output is off, and does not show hold time of data bus.
Hold time of data bus varies with capacitor volume and pull-up (pull-down) resistance value.
Hold time of data bus is expressed in
$t = -CR \times \ln (1 - V_{OL} / V_{CC})$
by a circuit of the right figure.
For example, when $V_{OL} = 0.2\ V_{CC}$, C = 30 pF, R =1 kΩ, hold time of output "L" level is
$t = -30\ pF \times 1\ k\Omega \times \ln (1 - 0.2\ V_{CC} / V_{CC}) = 6.7$ ns.

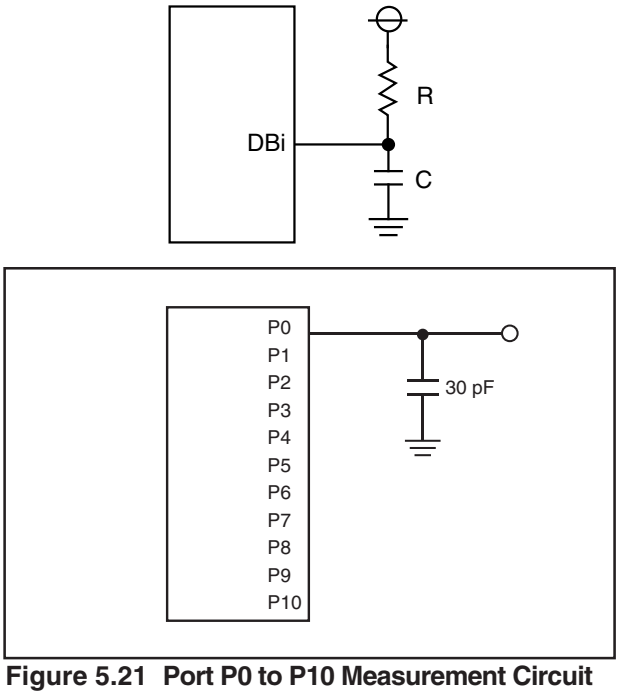


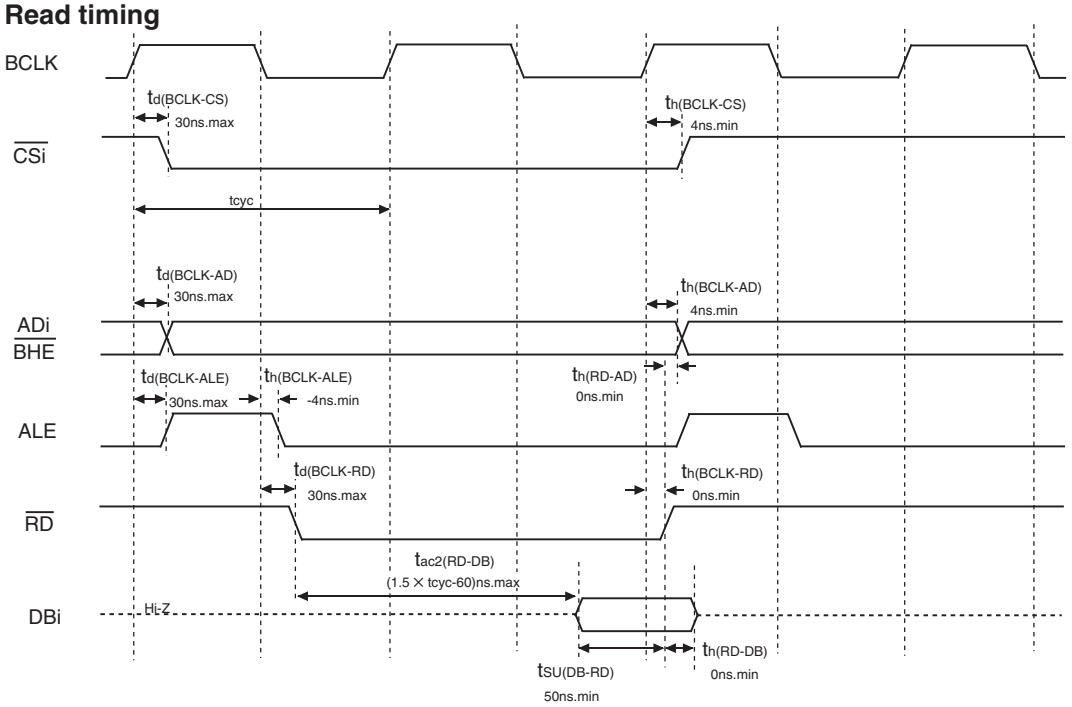
Figure 5.21 Port P0 to P10 Measurement Circuit

Memory Expansion Mode and Microprocessor Mode

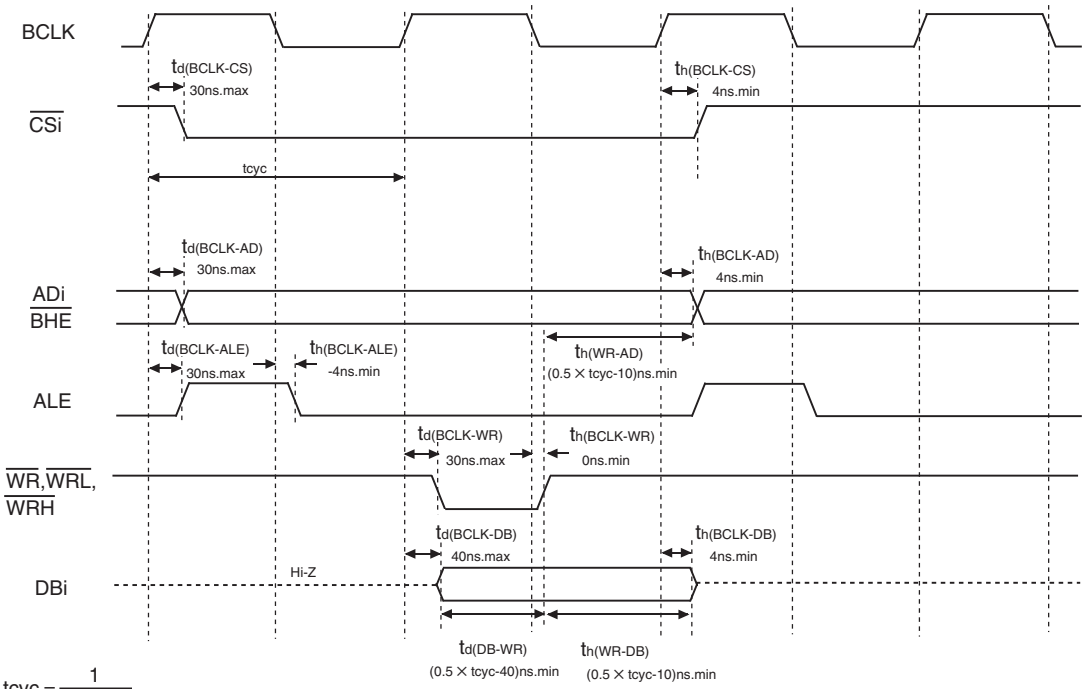
VCC = 3.3 V

(For 1-wait setting and external area access)

Read timing



Write timing



$$tcyc = \frac{1}{f(BCLK)}$$

Measuring conditions :

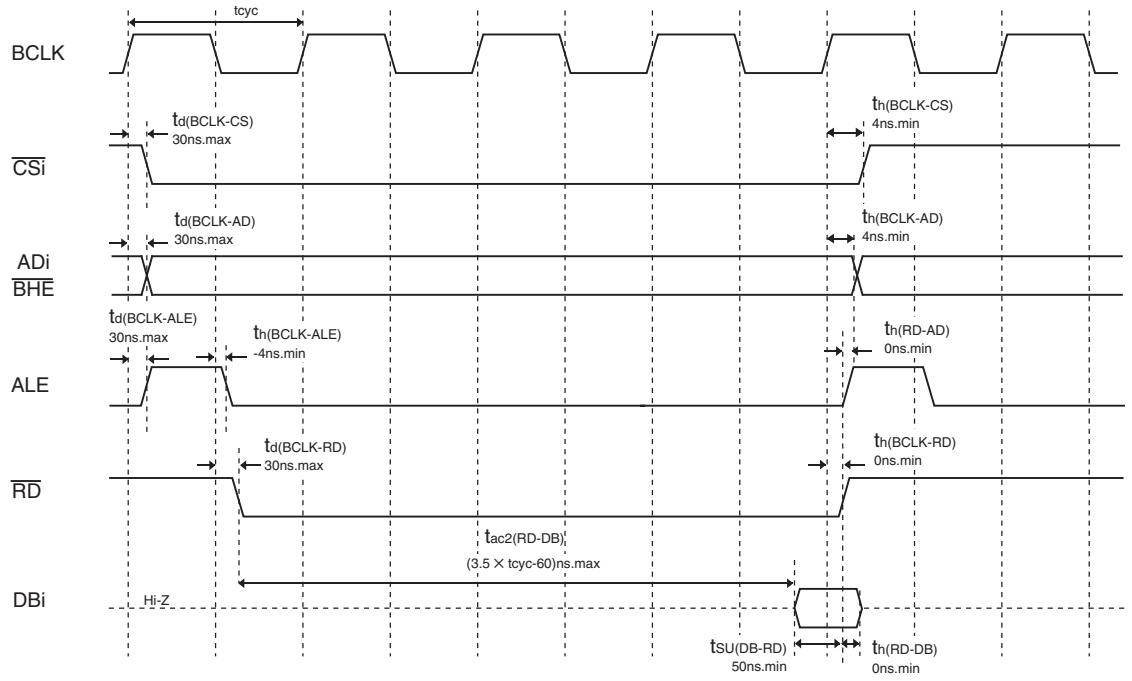
- VCC = 3.3 V
- Input timing voltage : V_{IL} = 0.6 V, V_{IH} = 2.7 V
- Output timing voltage : V_{OL} = 1.65 V, V_{OH} = 1.65 V

Figure 5.25 Timing Diagram (4)

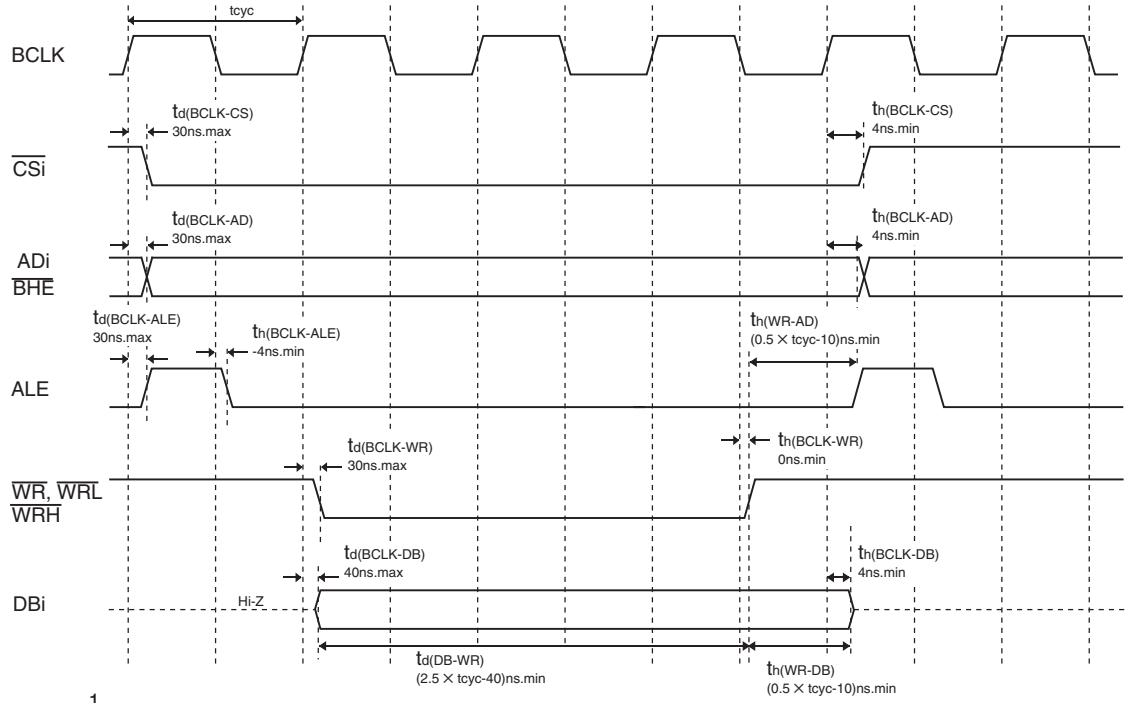
Memory Expansion Mode and Microprocessor Mode VCC = 3.3 V

(For 3-wait setting and external area access)

Read timing



Write timing



$$tcyc = \frac{1}{f(BCLK)}$$

Measuring conditions :

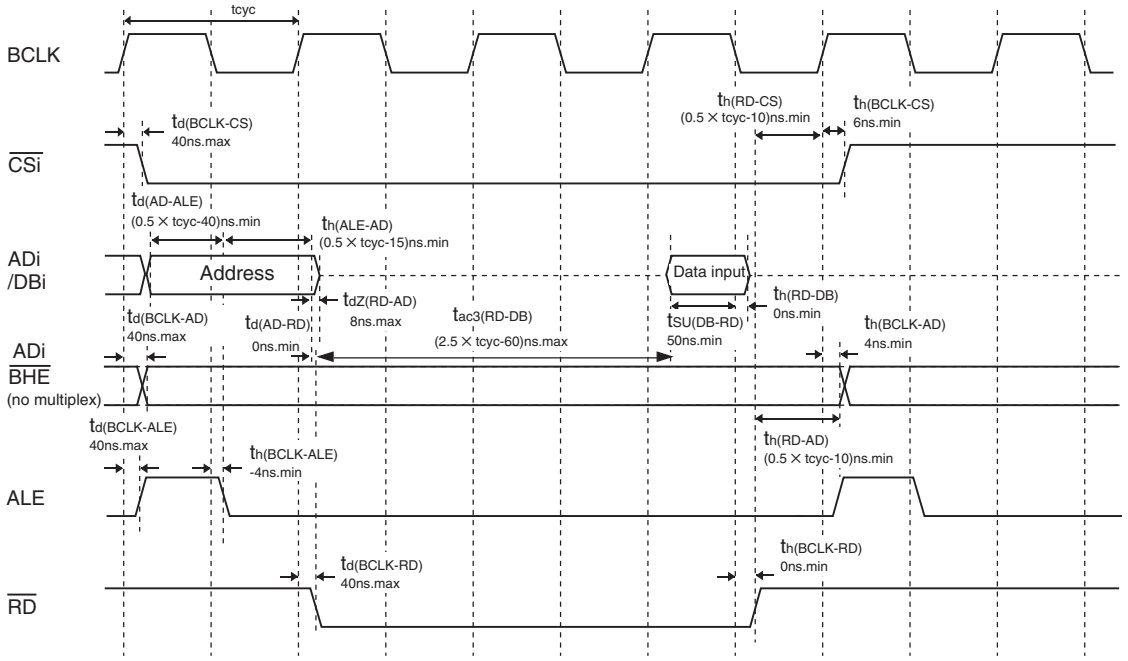
- VCC = 3.3 V
- Input timing voltage : V_{IL} = 0.6 V, V_{IH} = 2.7 V
- Output timing voltage : V_{OL} = 1.65 V, V_{OH} = 1.65 V

Figure 5.27 Timing Diagram (6)

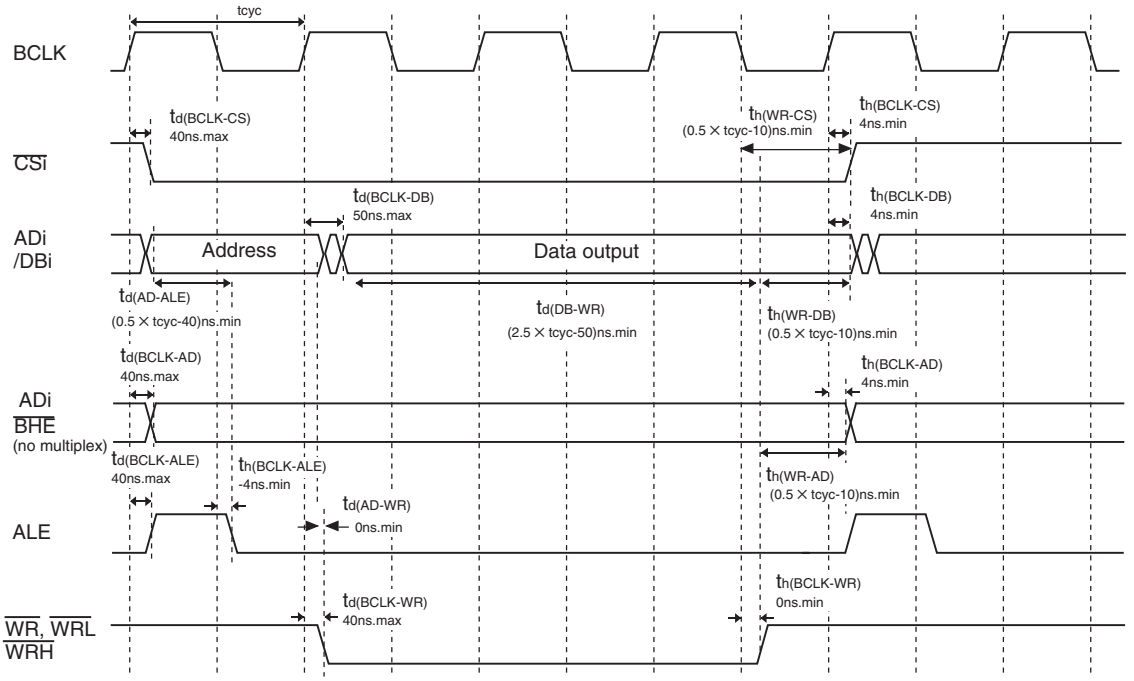
Memory Expansion Mode and Microprocessor Mode VCC = 3.3 V

(For 3-wait setting, external area access and multiplexed bus selection)

Read timing



Write timing



$$tcyc = \frac{1}{f(BCLK)}$$

Measuring conditions :

- VCC = 3.3 V
- Input timing voltage : V_{IL} = 0.6 V, V_{IH} = 2.7 V
- Output timing voltage : V_{OL} = 1.65 V, V_{OH} = 1.65 V

Figure 5.29 Timing Diagram (8)